IN THE CLAIMS

1. (Currently Amended) A [device mounting] method for mounting a plurality of elements comprising:

[a device separating step of] separating a plurality of devices, which have been arrayed [with a specific] at a first period on a [wafer] substrate, into individual [devices] elements while keeping the [arrayed state of the devices] first period as it is, wherein more than one but not all of the elements in a given row are separated from the substrate;

[a device re-arraying step of] handling the individually separated [devices] elements so as to re-array the [devices] elements at a second period having [at intervals of] a value equivalent to a multiple of the first period [multiplied by a specific magnification]; and

[a device transferring step of] transferring the re-arrayed [devices] elements on a mounting board, wherein the elements are mounted to the mounting board at a period equivalent to the second period [while keeping the re-arrayed state of the devices as it is].

2. (Currently Amended) A [device mounting] method according to claim 1, wherein said [device re-arraying step] handling comprises a [discrete selection procedure of] discretely selecting the [devices] elements [at intervals of] at a second period having a value equivalent to a multiple of the first period, wherein the multiple is an integer [multiplied by an integer magnification];

said [device] transferring [step comprises a partial transfer procedure of] comprising transferring the selected [devices] elements on a portion of the mounting board, wherein[; and] the plurality of [devices] elements are transferred on the entire surface of the mounting board by repeating said [discrete selection procedure] discrete selecting of elements and said [partial transfer procedure] transferring of the selected elements.

3. (Currently Amended) A [device mounting] method according to claim 2, wherein said [discrete selection procedure] discrete selecting of elements is carried out by peeling only [devices] elements, which are selected from the plurality of [devices] elements having been separated from each other on the surface of the [wafer] substrate with the [arrayed state] first period thereof kept as it is, from the [wafer] substrate by irradiating the selected [devices]

elements with an energy beam emitted from the back surface of the [wafer] substrate, and temporarily transferring the peeled [devices] elements on a temporary board, thereby re-arraying the peeled [devices] elements thereon; and

said [partial transfer procedure] transferring of the selected elements is carried out by finally transferring the [devices] elements temporarily transferred on the temporary board on the mounting board.

4. (Currently Amended) A [device mounting] method according to claim 1, wherein said [device] element re-arraying step comprises:

[a fixation procedure of] fixing the individually separated [devices] elements on a support enlargeable by a set multiple [at a specific magnification] while keeping the [arrayed state] first period of the [devices] elements as it is; and

[an enlargement procedure of] enlarging the support [at the specific magnification] by the set multiple, thereby re-arraying the [devices] elements [with intervals of] at a second period having a value equivalent to the first period multiplied by the set multiple[specific magnification].

5. (Currently Amended) A [device mounting] method according to claim 4, wherein said [fixation procedure] fixing is carried out by fixing the individually separated [devices] elements on a film-like support deformable by said set multiple[at said specific magnification]; and

said [enlargement procedure] enlarging is carried out by drawing the film-like support at said set multiple[specific magnification].

6. (Currently Amended) A [device mounting] method according to claim 4, wherein said [fixation procedure] fixing is carried out by fixing the individually separated [devices] elements on a support previously, repeatedly folded so as to be developable at said set multiple[specific magnification]; and

said [enlargement procedure] enlarging is carried out by developing the support at said set multiple[specific magnification].

7. (Currently Amended) A [device mounting] method according to claim 1, wherein said [device separation step] separating is carried out by separating a plurality of [devices] elements in such a manner that the [devices] elements are two-dimensionally arrayed [with a specific] at a first period in the longitudinal and lateral directions; and

said [device re-arraying step] handling is carried out by one-dimensionally re-arraying the [devices] elements in one of the longitudinal and lateral direction, and then one-dimensionally re-arraying the [devices] elements in the other of the longitudinal and lateral directions.

8. (Currently Amended) A [device mounting] method according to claim 1, wherein said [device re-arraying step] handling is carried out by performing a first re-array operation at a first magnification and then performing a second re-array operation at a second magnification, the product of the first magnification and the second magnification being equal to said specific magnification.

9. (Currently Amended) A [device mounting] method according to claim 1, wherein said [device separating step] separating is carried out by [integratedly] forming light emitting [devices] elements on a semiconductor [wafer] substrate and separating the light emitting [devices] elements into individual light emitting [devices] elements; and

said [device transferring step] transferring is carried out by transferring said light emitting [devices] elements at specific intervals on a mounting board of an image display.

10. (Currently Amended) A [device mounting] method comprising:

[a transfer step of] transferring a plurality of [devices] elements, which have been arrayed on a [wafer] substrate at initial intervals, on a mounting board[;],

wherein the [devices] elements are discretely mounted on the mounting board in such a manner as to be two-dimensionally re-arrayed [with scaled-up] at intervals greater than their initial intervals.

11. (New) A method for mounting a plurality of elements comprising:

separating a plurality of elements arrayed on a substrate from the substrate, wherein the elements have been arrayed on the substrate at a first period, and wherein more than one but not all of the elements in a given row are separated;

handling the individually separated elements so as to re-array the elements separated from the substrate at a second period equivalent to a multiple of the first period; and

transferring the re-arrayed elements on a mounting board.

12. (New) A method according to claim 11, wherein the separating is carried out by forming light emitting elements on a semiconductor substrate and separating the light emitting elements into individual light emitting elements, and wherein the transferring is carried out by transferring said light emitting elements at specific intervals on a mounting board of an image display.

13. (New) A method for mounting a plurality of elements comprising:

separating a plurality of elements arrayed on a substrate from the substrate, wherein the elements have been arrayed on the substrate at a first period;

handling the individually separated elements so as to re-array the elements separated from the substrate at a second period equivalent to a multiple of the first period, wherein the multiple is an integer greater than one; and

transferring the re-arrayed elements on a mounting board.

14. (New) A method according to claim 13, wherein the separating is carried out by forming light emitting elements on a semiconductor substrate and separating the light emitting elements into individual light emitting elements, and wherein the transferring is carried out by transferring said light emitting elements at specific intervals on a mounting board of an image display.

15. (New) A method for mounting a plurality of elements comprising:

separating a two-dimensional array of elements arrayed on a substrate from the substrate, wherein the elements have been arrayed on the substrate at a first period;

handling the individually separated elements so as to re-array the elements separated from the substrate at a second period equivalent to a multiple of the first period; and

transferring the re-arrayed elements on a mounting board.

16. A method according to claim 15, wherein the multiple is an integer greater than one.

17. (New) A method according to claim 15, wherein the separating is carried out by forming light emitting elements on a semiconductor substrate and separating the light emitting elements into individual light emitting elements, and wherein the transferring is carried out by transferring said light emitting elements at specific intervals on a mounting board of an image display.